Special Issue

Integrated Circuits for Systems on Chip and Systems in Package towards Advanced Industrial Applications

Message from the Guest Editors

This Special Issue is to focus on the recent developments in reconfigurable and integrated circuits including the design, implementation and measurements of SoC and SiP for sensor interfaces and industrial applications. This includes (but is not limited to) high-voltage circuits (on-chip digital isolators, power amplifiers, level shifters ...) and low-voltage circuits (data converters, read-back circuits, filters ...). Research works based on advanced packaging solutions for SoC and SiP are welcomed for this Special Issue. Authors are invited to submit their latest research findings (including simulation and measurement results) for publication. Both regular articles and review papers are welcomed. The deadline to submit papers to this special issue is 31 March 2023. However, papers submitted in advance will be peer-reviewed and may be published well before this deadline. For more details, please click here.

Guest Editors

Dr. Ahmad Hassan

Dr. Mohamed Ali

Dr. Ali Roshanghias

Deadline for manuscript submissions

closed (31 March 2023)

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Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Editor-in-Chief

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